

In The Claims:

Please cancel Claims 1-12 and amend claims 13-24 as follows:

Claims:

1-12 (cancelled)

13. (original) A semiconductor device formed by the process of:

(a) applying an electrically non-conductive material covering at least a portion of said die and extending onto said substrate to a plurality of contact pads formed on said substrate; and

(b) applying an electrically conductive material over said non-conductive material and extending from an electrical point of contact of said die to at least one contact pad on said substrate.

14. (original) A device as claimed in claim 13, wherein the conductive material is separated into a plurality of conductive patches by laser trimming away portions of the conductive material.

15. (original) A device as claimed in claim 13, wherein a hole is trimmed into the non-conductive material over and down to the bond pads, exposing at least a portion of each bond pad to be connected.

16. (original) A device as claimed in claim 13, wherein an electrically conductive bump is formed on each said die bond pad, said bump protruding through said non-conductive material and at least partially through said conductive material.
17. (original) A device as claimed in claim 13, wherein the insulating layer comprises a non-conductive epoxy.
18. (original) A device as claimed in claim 13, wherein the insulating layer comprises a non-conductive polyimide.
19. (original) A device as claimed in claim 13, wherein the conductive layer comprises conductive ink.
20. (original) A device as claimed in claim 13, wherein the conductive layer comprises a metal ion coating.
21. (original) A device as claimed in claim 13, wherein (a) includes spinning the non-conductive material onto the die and package substrate.
22. (original) A device as claimed in claim 13, wherein (a) includes spraying the non-conductive material onto the die and package substrate.

23. (original) A device as claimed in claim 13, wherein (b) includes spinning the non-conductive material onto the die and package substrate.

24. (original) A device as claimed in claim 13, wherein (b) includes spraying the non-conductive material onto the die and package substrate.